Compound Semiconductor Materials Japan TC Chapter Meeting

Japan Standards Spring Meetings 2024

Tuesday, May 21, 2024

Room 2, SEMI Japan, Tokyo Japan/ Official Virtual TC Chapter Meeting (Hybrid)

14:00-16:00 JST

AGENDA

1 Welcome/Call to Order

1.1 Introductions

1.2 Required Elements (Membership Requirements, Antitrust and Intellectual Property Reminders, and Effective Meeting Guidelines)

1.3 Agenda Review

2 Review of Previous Meeting Minutes

3 Liaison Report

3.1 JRSC Report

3.2 GCS Report

3.3 Europe TC Chapter

3.4 North America TC Chapter

3.5 China TC Chapter

4 Staff Report

5 Ballot Review

5.1 Document 7211 — Line Item Revisions To SEMI M92-0423, Specification For 4H-SiC Homoepitaxial Wafer

6 Subcommittee & Task Force Reports

6.1 Silicon Carbide Substrate Liaison Task Force

6.2 SiC Epitaxial Wafer Liaison Task Force

7 Old Business

7.1 Project Period Review

7.2 5-year Review

8 New Business

9 Action Item Review

9.1 Open Action Items

Item #	*Assigned to*	*Details*
20220119-01	SEMI Staff	To confirm China SEMI Staff that two JA members (Masayoshi Obara and Toshimasa Yamamoto) surely are registered in China Sic Epitaxial Water TF and China Silicon Carbide Substrate TF.
20220119-02	SEMI Staff	To ask China TF leaders to contact above JA members through SEMI China Staff about Documents #6693, 6767-9.
20220119-03	Silicon Carbide Substrate Liaison TF leaders and SiC Epitaxial Wafer Liaison TF leaders	To confirm the contents of Document #6693, 6767-9 and their ballot schedule and share them to the JA TF members and hold meetings as necessary.

9.2 New Action Items

Item #	*Assigned to*	*Details*

10 Next Meeting and Adjournment

10.1 The next meeting is scheduled for <date> at <event/location>.